TOSHIBA Power Transistor Module Silicon Triple Diffused Type (Four Darlington Power Transistors inOne)

MP4507

High Power Switching Applications
Hammer Drive, Pulse Motor Drive and Inductive
Load Switching

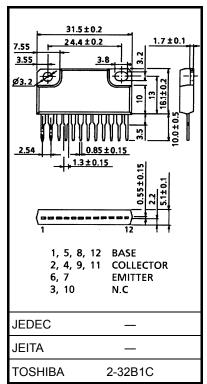
- Package with heat sink isolated to lead (SIP 12 pins)
- High collector power dissipation (4-device operation) : $P_T = 5$ W ($T_a = 25^{\circ}$ C)
- High collector current: IC (DC) = ± 5 A (max)
- High DC current gain: $h_{FE} = 1000$ (min) ($V_{CE} = \pm 3$ V, $I_{C} = \pm 3$ A)

Maximum Ratings (Ta = 25°C)

Characteristi	Cumbal	Rat	Unit			
Characteristi	Symbol	NPN	PNP	Offic		
Collector-base voltage	V _{CBO}	100	-100	V		
Collector-emitter voltage		V _{CEO}	100	-100	V	
Emitter-base voltage		V _{EBO}	5	-5	>	
Collector current	DC	IC	5	-5	Α	
	Pulse	I _{CP}	8 -8			
Continuous base current	Continuous base current			-0.1	Α	
Collector power dissipati	Collector power dissipation			3.0		
(1-device operation)		PC	,	W		
Collector power dissipation	Ta = 25°C	PC	5.0		W	
(4-device operation)	Tc = 25°C	10	25			
Isolation voltage	V _{Isol}	1000		V		
Junction temperature	Tj	150		°C		
Storage temperature ran	T _{stg}	-55 to 150		°C		

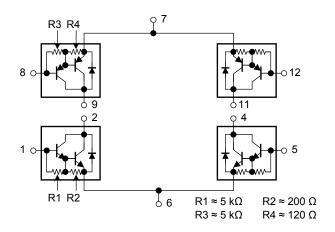
Industrial Applications

Unit: mm



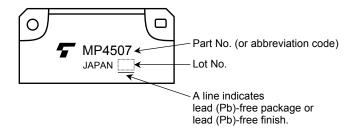
Weight: 6.0 g (typ.)

Array Configuration



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Marking



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance fromchannel to ambient (4 devices operation, Ta = 25°C)	ΣR _{th (j-a)}	25	°C/W
Thermal resistance from channel to case (4 devices operation, Tc = 25°C)	ΣR _{th (j-c)}	5.0	°C/W
Maximum lead temperature for soldering purposes (3.2 mm from case for 10 s)	TL	260	°C

Electrical Characteristics (Ta = 25°C) (NPN transistor)

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off current		I _{CBO}	V _{CB} = 100 V, I _E = 0 A	_	_	10	μΑ
Collector cut-off cu	rrent	I _{CEO}	V _{CE} = 100 V, I _B = 0 A	_	_	10	μA
Emitter cut-off curr	ent	I _{EBO}	V _{EB} = 5 V, I _C = 0 A	0.3	_	2.0	mA
Collector-base brea	akdown voltage	V (BR) CBO	I _C = 1 mA, I _E = 0 A	100	_	_	V
Collector-emitter bi	reakdown voltage	V (BR) CEO	I _C = 30 mA, I _B = 0 A	100	_	_	V
DC surrent sein		h _{FE (1)}	V _{CE} = 3 V, I _C = 0.5 A	1000	_	_	
DC current gain		h _{FE (2)}	V _{CE} = 3 V, I _C = 3 A	1000	_	_	_
Caturation voltage	Collector-emitter	V _{CE} (sat)	I _C = 3 A, I _B = 12 mA	_	_	2.0	V
Saturation voltage	Base-emitter	V _{BE (sat)}	I _C = 3 A, I _B = 12 mA	_	_	2.5	
Transition frequency		f _T	V _{CE} = 3 V, I _C = 0.5 A	3	_	_	MHz
Collector output capacitance		C _{ob}	V _{CB} = 50 V, I _E = 0 A, f = 1 MHz	_	40	_	pF
	Turn-on time	t _{on}	Output Input B1 C 20 µs B2 W VCC = 30 V	_	0.5	_	
	Storage time	t _{stg}		_	3.0	_	μs
	Fall time	t _f	$I_{B1} = -I_{B2} = 12 \text{ mA, duty cycle} \le 1\%$	_	2.0	_	



Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I _{FM}	_	_	_	5	Α
Surge current	I _{FSM}	t = 1 s, 1 shot	_	_	8	Α
Forward voltage	V _F	I _F = 1 A, I _B = 0 A	_	_	2.0	٧
Reverse recovery time	t _{rr}	$I_F = 5 \text{ A}, V_{BE} = -3 \text{ V}, dI_F/dt = -50 \text{ A/}\mu\text{s}$	_	1.0	_	μs
Reverse recovery charge	Q _{rr}		_	8	_	μC

Electrical Characteristics (Ta = 25°C) (PNP transistor)

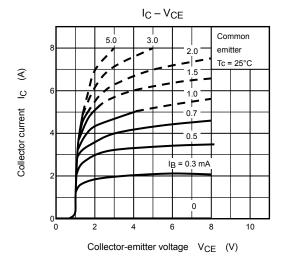
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off cu	rrent	I _{CBO}	V _{CB} = -100 V, I _E = 0 A	_	_	-10	μΑ
Collector cut-off cu	rrent	I _{CEO}	V _{CE} = -100 V, I _B = 0 A	_	_	-10	μA
Emitter cut-off curr	ent	I _{EBO}	$V_{EB} = -5 \text{ V}, I_C = 0 \text{ A}$	-0.3	_	-2.0	mA
Collector-base brea	akdown voltage	V (BR) CBO	I _C = -1 mA, I _E = 0 A	-100	_	_	V
Collector-emitter b	reakdown voltage	V (BR) CEO	I _C = -30 mA, I _B = 0 A	-100	_	_	٧
DC surrent sein		h _{FE (1)}	$V_{CE} = -3 \text{ V}, I_{C} = -0.5 \text{ A}$	1000	_	_	
DC current gain		h _{FE} (2)	V _{CE} = -3 V, I _C = -3 A	1000	_	_	_
Caturation valtage	Collector-emitter	V _{CE (sat)}	I _C = -3 A, I _B = -12 mA	_	_	-2.0	V
Saturation voltage	Base-emitter	V _{BE (sat)}	I _C = -3 A, I _B = -12 mA	_	_	-2.5	
Transition frequency		f _T	V _{CE} = -3 V, I _C = -0.5 A	3	_	_	MHz
Collector output ca	Collector output capacitance		V _{CB} = -50 V, I _E = 0 A, f = 1 MHz	_	40	_	pF
Switching time Storag	Turn-on time	t _{on}	Output IB2	_	0.5	_	
	Storage time	t _{stg}	Input 32 20 μs IB1 W 30	_	3.0	_	μs
	Fall time	t _f	$V_{CC} = -30 \text{ V}$ $-I_{B1} = I_{B2} = 12 \text{ mA}, \text{ duty cycle} \le 1\%$	_	2.0	_	

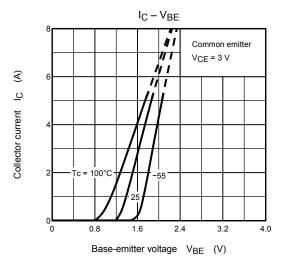
Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

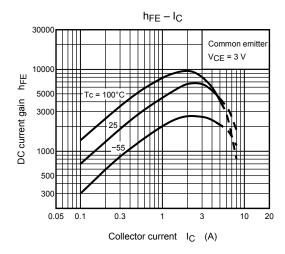
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I _{FM}	_	_	_	5	Α
Surge current	I _{FSM}	t = 1 s, 1 shot	_	_	8	Α
Forward voltage	V _F	I _F = 1 A, I _B = 0 A	_	_	2.0	V
Reverse recovery time	t _{rr}	I _F = 5 A, V _{BE} = 3 V, dI _F /dt = -50 A/μs	_	1.0	_	μs
Reverse recovery charge	Q _{rr}			8	_	μC

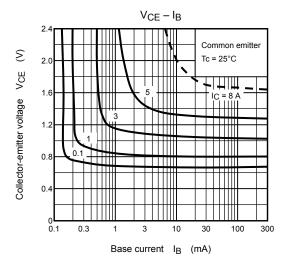
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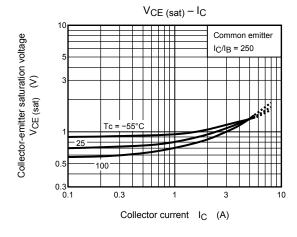
(NPN transistor)

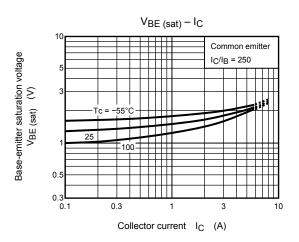




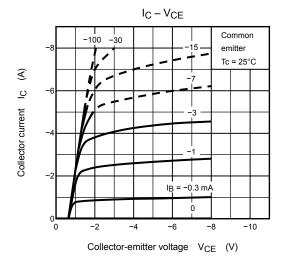


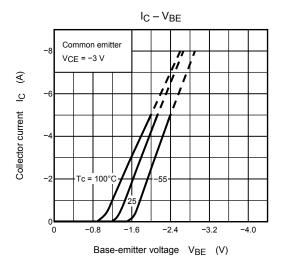


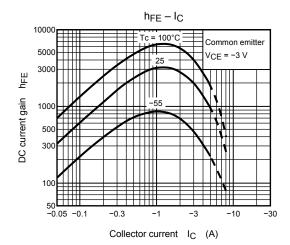


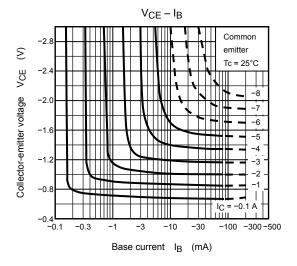


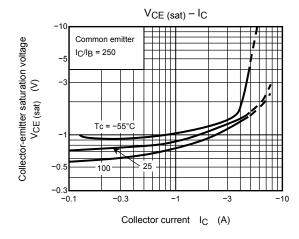
(PNP transistor)

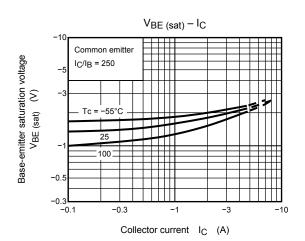




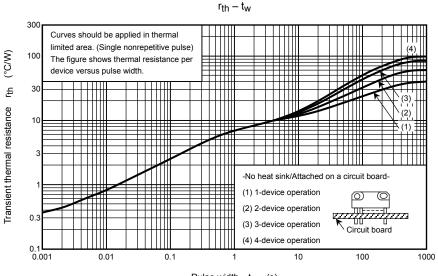




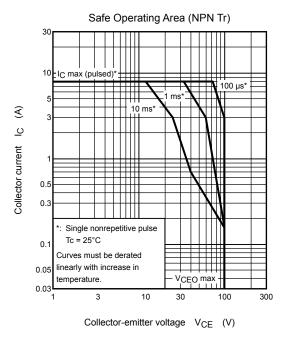


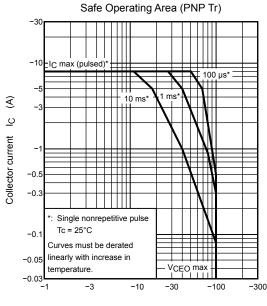


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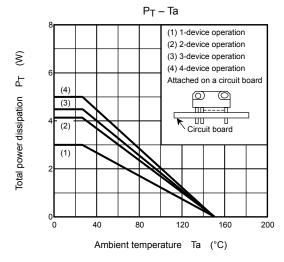


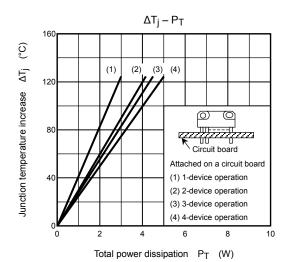






Collector-emitter voltage V_{CE} (V)





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